

07-29-1999

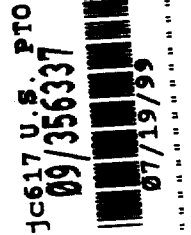


101104775

PATENT

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

REQUEST FOR ASSIGNMENT RECORDAL



Box Assignments  
Honorable Commissioner of Patents and Trademarks  
Washington, D.C. 20231

Dear Sir:

Please record the attached assignment document.

1. Names of conveying parties: TSUKASA OOISHI and HIROYA NAKAMURA
2. Name and address of receiving party: Mitsubishi Denki Kabushiki Kaisha  
2-3, Marunouchi 2-chome,  
Chiyoda-ku, Tokyo 100-8310,  
JAPAN and Texas Instruments  
Incorporated, 7839 Churchill Way,  
Dallas, Texas 75251, U.S.A.
3. Nature of conveyance: Assignment  
Execution Date: July 5, 1999
4. Application No.:  
The execution date of the patent application is July 5, 1999.
5. Name and address of party to whom correspondence concerning the attached document should be mailed:

LEYDIG, VOIT & MAYER  
Suite 300  
700 Thirteenth Street, N.W.  
Washington, D.C. 20005

400281/FUKAMI

6. Total number of patent applications involved: 1

7. Total fee: \$40.00

☒ Enclosed

☐ Authorized to be charged to the deposit account

☒ The Commissioner is authorized to charge any deficiencies in the fee payment accompanying this communication and to credit any excess payment of fees to Deposit Account No. 12-1216.

8. Statement and signature

To the best of my knowledge and belief, the foregoing information is true and correct and any attached copy is a true copy of the original document.

July 19, 1994  
Date

Jeffrey A. Wyand  
Jeffrey A. Wyand  
Registration No. 29,458

Total number of pages comprising cover sheet, attachments and document: 4

400281/FUKAMI

ATTORNEY DOCKET NO.

## ASSIGNMENT

Application No. \_\_\_\_\_

Filed \_\_\_\_\_

Insert Name(s)  
of Inventor(s) ➡

WHEREAS, Tsukasa OOISHI and Hiroya NAKAMURA

\_\_\_\_\_  
\_\_\_\_\_  
\_\_\_\_\_

(hereinafter designated as the undersigned) has (have) invented certain new and useful improvements in \_\_\_\_\_

Insert Title  
of Invention ➡

SYNCHRONOUS SEMICONDUCTOR ALLOWING REPLACEMENT WITH  
REDUNDANT MEMORY CELL WHILE MAINTAINING ACCESS TIME

for which an application for Letters Patent of the United States of America has been executed by the undersigned

Insert Date  
of Signing of  
Application ➡

on July 5, 1999; and

Insert Name  
of Assignee ➡

WHEREAS, Mitsubishi Denki Kabushiki Kaisha and  
Texas Instruments Incorporated

\_\_\_\_\_

Insert Address  
of Assignee ➡

of 2-3, Marunouchi 2-Chome, Chiyoda-ku, TOKYO 100-8310 JAPAN and

7839 Churchill Way, Dallas, Texas 75251, USA, respectively

its heirs, successors, legal representatives and assigns (hereinafter designated as the Assignee) is desirous of  
acquiring the entire right, title and interest in and to said invention and in and to any Letters Patent(s) that  
may be granted therefor in the United States of America and

CHECK BOX  
IF APPROPRIATE ➡

☒ in any and all foreign countries.

NOW, THEREFORE, in consideration of the sum of Ten Dollars (\$10.00) to the undersigned in hand paid, the receipt of which is hereby acknowledged, and other good and valuable consideration, the undersigned has (have) sold, assigned and transferred, and by these presents does sell, assign and transfer unto said Assignee the full and exclusive right to the said invention in the United States of America, its territories, dependencies and possessions and the entire right, title and interest in and to any and all Letters Patent(s) which may be granted therefor in the United States of America, its territories, dependencies and possessions, and if the box above is designated, in any and all foreign countries;

and to any and all divisions, reissues, continuations and extensions thereof for the full term or terms for which the same may be granted.

The undersigned agree(s) to execute all papers necessary in connection with this application and any continuing, divisional or reissue applications thereof and also to execute separate assignments in connection with such applications as the Assignee may deem necessary or expedient.

The undersigned agree(s) to execute all papers necessary in connection with any interference which may be declared concerning this application or continuation, division or reissue thereof or Letters Patent(s) or reissue patent issued thereon and to cooperate with the Assignee in every way possible in obtaining and producing evidence and proceeding with such interference.

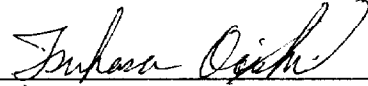
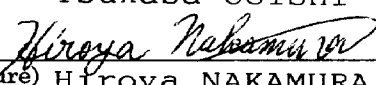
The undersigned agree(s) to execute all papers and documents and to perform any act which may be necessary in connection with claims or provisions of the International Convention for the Protection of Industrial Property or similar agreements.

The undersigned agree(s) to perform all affirmative acts which may be necessary to obtain a grant of a valid United States of America patent(s) or a grant of a valid United States of America and any foreign patent(s) to the Assignee and to vest all rights therein hereby conveyed to said Assignee as fully and entirely as the same would have been held by the undersigned if this Assignment and sale had not been made.

The undersigned hereby authorize(s) the request(s) the Patent and Trademark Office Officials in the United States of America and in any foreign countries to issue any and all Letters Patents resulting from said application or any continuing, divisional or reissue applications thereof to the said Assignee, as Assignee of the entire interest, and hereby covenants that he has (they have) the full right to convey the entire interest herein assigned, and that he has (they have) not executed, and will not execute, any agreement in conflict herewith.

The undersigned hereby grant(s) the law firm of Leydig, Voit & Mayer the power to insert on this Assignment any further identification which may be necessary or desirable in order to comply with the rules of the U.S. Patent and Trademark Office for recordation of this document.

The undersigned hereby covenant(s) that no assignment, sale, agreement or encumbrance has been or will be made or entered into which would conflict with this assignment.

Date <u>July 5, 1999</u>	Name of Inventor <u></u> (signature) Tsukasa OOISHI
Date <u>July 5, 1999</u>	Name of Inventor <u></u> (signature) Hiroya NAKAMURA
Date _____	Name of Inventor _____ (signature)
Date _____	Name of Inventor _____ (signature)
Date _____	Name of Inventor _____ (signature)
Date _____	Name of Inventor _____ (signature)
Date _____	Name of Inventor _____ (signature)
Date _____	Name of Inventor _____ (signature)
Date _____	Name of Inventor _____ (signature)